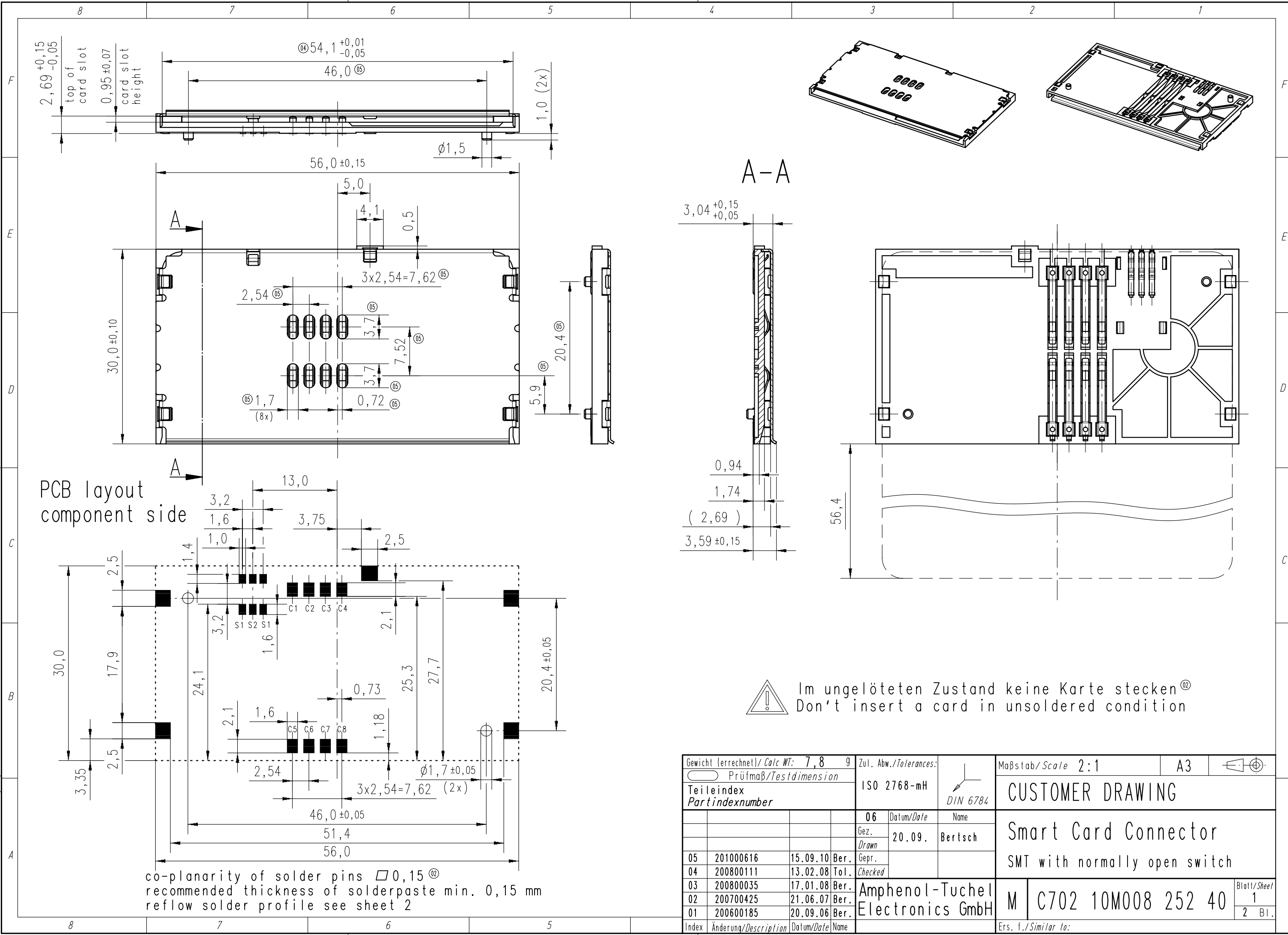


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Im ungelöteten Zustand keine Karte stecken®
 Don't insert a card in unsoldered condition

co-planarity of solder pins $\square 0,15$ ®
 recommended thickness of solderpaste min. 0,15 mm
 reflow solder profile see sheet 2

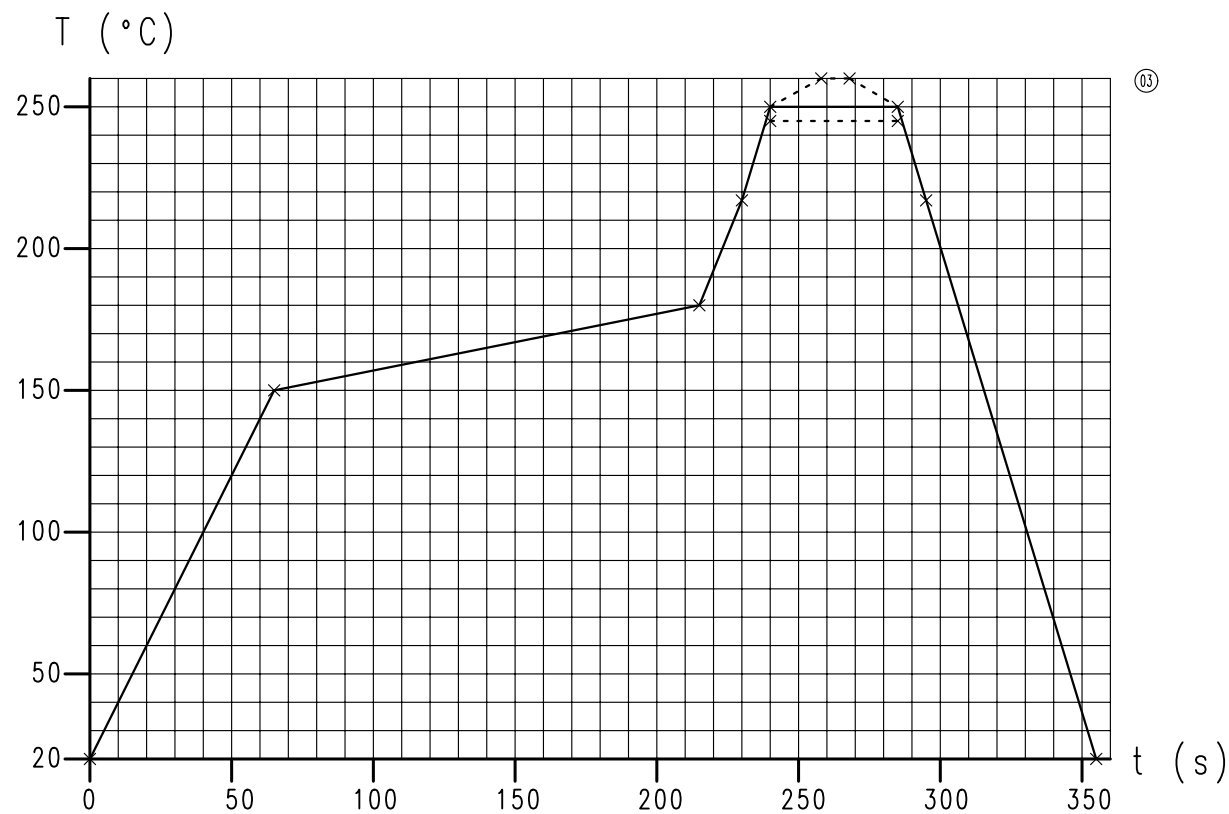
Gewicht (errechnet) / Calc WT: 7,8 9		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1		A3	
Prüfmaß / Testdimension		ISO 2768-mH		DIN 6784		CUSTOMER DRAWING	
Teileindex Partindexnumber		06		Datum / Date		Name	
		Gez.		20.09.		Bertsch	
		Drawn					
		Gepr.					
05 201000616 15.09.10 Ber.		03 200800035 17.01.08 Ber.		Amphenol-Tuchel		Blatt / Sheet	
04 200800111 13.02.08 Tol.		02 200700425 21.06.07 Ber.		Electronics GmbH		1	
01 200600185 20.09.06 Ber.						2 Bl.	
Index Änderung / Description Datum / Date Name						Ers. f. / Similar to:	

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estimated temperature profile for lead free soldering^{02 03}

Sn (3,0-4,0)Ag (0,5-0,9)Cu solder alloy



Parameter	Specification
Average temperature gradient in preheating	2,5 °C/s
Preheating temperature	150 °C - 200 °C
Soak time	120 s - 180 s
Time above 217 °C	40 s - 120 s
Peak temperature in reflow	245 °C - 260 °C ⁰³
Time at peak temperature	10 s - 50 s
Temperature gradient in cooling	max -5 °C/s

Specification⁰²

DESIGN

type: push-pull, wiping contacts
normally open switch
with positioning studs

GENERAL CHARACTERISTICS

number of contacts: 8 contacts
switch: normally open (no card inserted)
card type: according to ISO 7810 / 7816
card thickness: 0,76 ±0,08 mm
termination: SMT

MATERIALS AND PLATING

insulator: LCP, black
contact plating: Au over Ni

CLIMATIC CHARACTERISTICS

operating temperature: -25 °C to +70 °C
storage temperature: -40 °C to +85 °C
soldering process: reflow soldering

ELECTRICAL CHARACTERISTICS

contact resistance: max. 100 mΩ (data contacts)
max. 1 Ω (switch)
insulation resistance: >10⁹ Ω
high voltage resistance: 500 V AC for 1 minute
rated voltage: <15 V DC
rated current: <1 A

MECHANICAL CHARACTERISTICS

card insertion force: <10 N
card extraction force: >1 N
mechanical lifetime: 100.000 mating cycles
(without corrosion stress)

PACKAGING

packaging: 32 parts per tray
24 trays per carton

Gewicht (errechnet) / Calc WT: 7,8 g		Zul. Abw. / Tolerances:		Maßstab / Scale 2:1		A3			
Prüfmaß / Testdimension		ISO 2768-mH				CUSTOMER DRAWING			
Teileindex Part index number		06		Datum / Date		Name		Smart Card Connector	
		Gez.		20.09.		Bertsch		SMT with normally open switch	
05 201000616		15.09.10		Ber.					
04 200800111		13.02.08		ToI.		Checked			
03 200800035		17.01.08		Ber.					
02 200700425		21.06.07		Ber.					
01 200600185		20.09.06		Ber.					
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								Blatt / Sheet 2 Bl.	
								Ers. f. / Similar to:	